



Advances in Modeling Caloric Cooling Devices

Guest Editor:

Dr. Daniel Silva

IFIMUP - Institute of Physics for
Advanced Materials,
Nanotechnology and Photonics,
Faculty of Science of the Porto
University, P-4169007 Porto,
Portugal

Deadline for manuscript
submissions:

closed (20 November 2022)

Message from the Guest Editor

Dear Colleagues,

We are inviting submissions to the Special Issue on Advances in Modeling Caloric Cooling Devices.

The current necessity of finding ways to mitigate the effects of global warming, provoked by human activity, has led to a steep increase in the development of advanced heat-management systems. In this context, a considerable fraction of the innovative cooling systems being developed are caloric cooling devices. Due to the large number of possibilities regarding the development of caloric cooling cycles, modeling them is of paramount importance when designing effective systems. In this Special Issue, we invite submissions exploring the modeling of advanced cooling devices, including the use of caloric technologies such as magnetocaloric, electrocaloric, elastocaloric and barocaloric materials. Since the validation of developed models is critical, experimental works that include the modeling of one or more components of these systems are also welcome. This Special Issue accepts both survey papers and comprehensive reviews.

Dr. Daniel Silva
Guest Editor





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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Applied Sciences Editorial Office
MDPI, St. Alban-Anlage 66
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